



ABSTRACT OF THE DISCLOSURE

POLYFUNCTIONAL CYANATE RESIN COMPOSITION AND RESIN-ENCAPSULATED TYPE SEMICONDUCTOR DEVICE

Provided is a polyfunctional cyanate resin composition comprising (A) a polyfunctional cyanate resin having a functional number of 2 or more or its prepolymer, (B) an epoxy resin having a softening point or melting point of 75 °C or more, and (C) a curing catalyst as indispensable components, and a resin-encapsulated type semiconductor device using the same, which has a high heat resistant property, a low coefficient of thermal expansion, and an excellent blocking resistance of a resin compound.